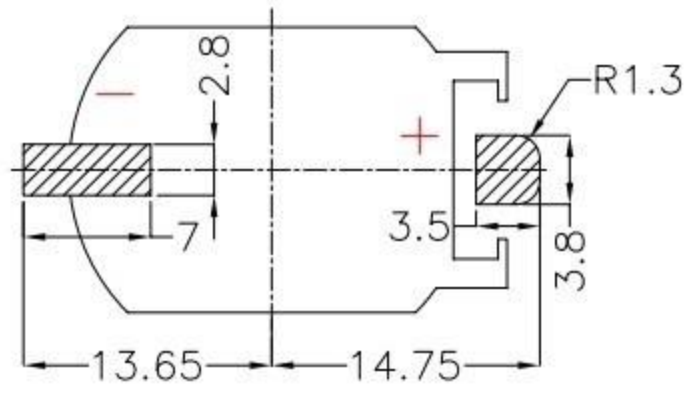
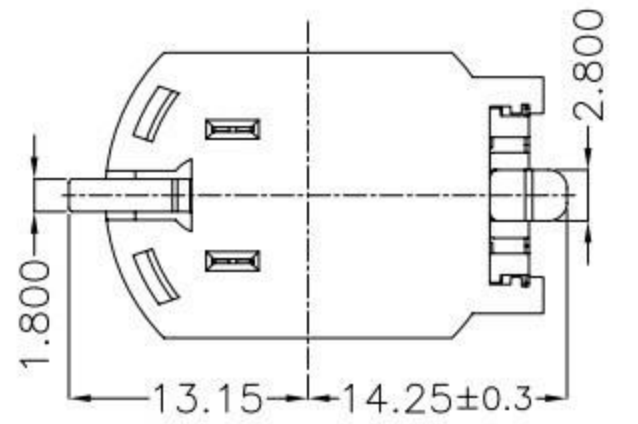
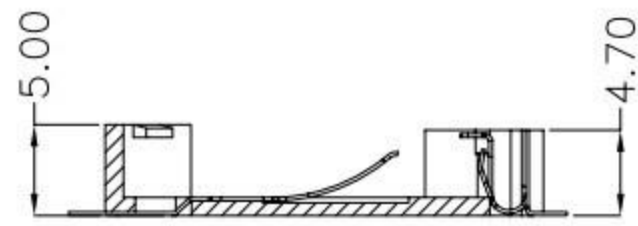
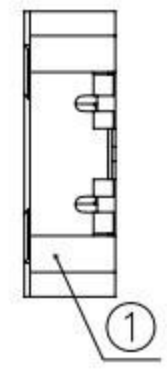
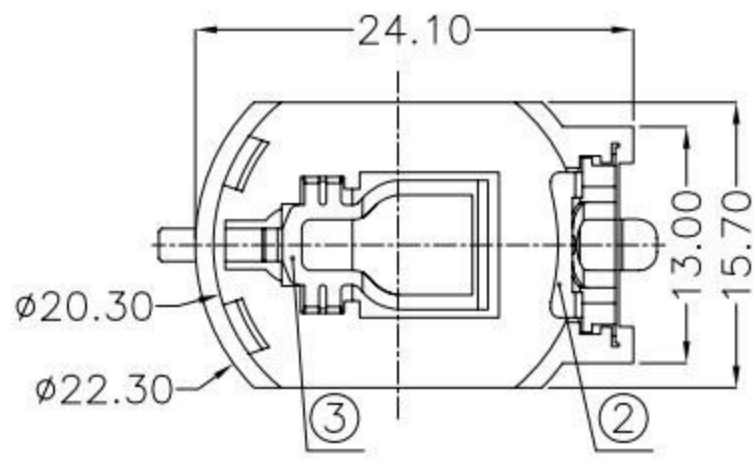




REV.	ECN NO.	REVISED	DATE



PCB Layout Diagram  
Top View

NOTE:

- 1.MATERIAL:  
a.HOUSING:PPA  
b.CONTACT:PHOSPHOR BRONZE  
(SURFACE PLATING: Au1u")  
SEE ORDERING INFORMATION
- 2.ELECTRIC:  
a.CONTACT RESISTANCE: 30 MILLIOHMS MAX  
b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN  
c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL  
d.OPERATING TEMPERATURE: -25° C~ +85° C

ORDERING INFORMATION

- 电池座系列
- SMT 180° TYPE
- PLATING:  
A-Au1u"  
J-Ni100U"~120U"  
K-Sn100U"~120U"
- MATERIAL:  
1A-PBT BLACK  
1B-PA66 BLACK  
2A-PPA BROWN  
2B-PPA BLACK  
3A-PPS BROWN  
3B-PPS BLACK  
4A-LCP WHITE  
4B-LCP BLACK

3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BLACK
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.30 X.X :±0.25 X.XX :±0.20 X.XXX :±0.10

ANGLES: X :±1° X.X :±0.5°

**廣東科斯達電子科技有限公司**

DSND	DATE	2017-06-29	TITLE:
CHKD	DATE	2017-06-29	
APVD	DATE	2017-06-29	PART NO.:
WEIGHT: 0.78g	SCALE: 2:1	SIZE: A4	VIEW:
SHEET 1 OF 1	UNIT: mm	REV.: A/0	OBJECT: MY
			DRAW NO.: